

### REMARKS

Applicants request favorable reconsideration and allowance of the subject application in view of the preceding amendments and the following remarks.

Claims 35 through 43 are presented for examination. Claims 35 through 39 have been cancelled without prejudice or disclaimer of subject matter. Claims 40 and 41 have been amended to define still more clearly what Applicants regard as their invention, in terms which distinguish over the art of record. Claim 40 is the only independent claim.

In the Office Action mailed February 26, 2003, Claim 40 was rejected under 35 U.S.C. § 112, second paragraph, as indefinite. In particular, Claim 40 was objected to in that the phrase "and on a side opposing another substrate" is vague and indefinite as to what it refers to, the phrase "which is one of the substrates when the plurality of substrates are arranged" is vague and indefinite as to what is being set forth, and the phrase "a cutting position" is vague and indefinite as to whether it refers to a previously recited or another such cutting position.

The objected-to phrases "and on a side opposing another substrate" and "which is one of the substrates when the plurality of substrates are arranged" in Claim 40 as currently amended have been deleted and the objected-to second occurring phrase "a cutting position" in the claim has been changed to "the cutting position". In view of these changes, Claims 40 through 43 as currently amended are believed to fully meet the requirements of 35 U.S.C. § 112, second paragraph.

Claims 40 through 43 were rejected in the Office Action mailed February 26, 2003 as unpatentable over U.S. Patent 3,398,620 (Gautron). With regard to Claims 40 through 43 as currently amended, this rejection is respectfully traversed.

Independent Claim 40 as currently amended is directed to a method of cutting an insulating substrate on which two-dimensionally arranged thin film semiconductor elements are installed. According to the cutting method, at least a slice line provided on the insulating substrate is cut while detecting a misalignment of a cutting position from the slice line and correcting the cutting position. The insulating substrate is cut on a side opposing the slice line without correcting the cutting position on the side opposing the slice line. After the cutting step is completed, a monitor line having an electrical conductor and provided on a side where the thin film semiconductors are installed is electrically checked.

In Applicants' view, Gautron discloses a sheet material cutting apparatus that has pivotally mounted shears for cutting the sheet material and a unit to move the sheet material relative to the shears. The sheet material is loosely guided with respect to the shears and a unit is provided that is responsive to angular variations of the sheet material to adjust the angle of the shears.

According to the invention of Claim 40 as currently amended, the side of an insulating substrate opposing a slice line is cut without correcting the cutting position of the side opposing the slice line. A monitor line having an electrical conductor provided on a

side of the substrate where thin film semiconductor elements are installed is electrically checked after the cutting is completed.

Gautron is directed to cutting out material in steel sheets by shearing (lines 24 and 25 of column 1) and provides an electrically-conductive guiding wire 13 for the cutting of a steel sheet (lines 8-11 of column 4). As clearly disclosed at lines 45-71 of column 4 with respect to Figs. 1 and 2, the guide wire 13 is suspended between electrodes 15 and 16. If the electrode 15 contacts the guide wire 13 during the cutting, the shearing direction is changed in one direction and if the electrode 16 contacts the guide wire 13 during the cutting, the shearing direction is changed in the opposite direction. Accordingly, there is no teaching or suggestion in Gautron of any electrical checking of a monitor line comprising an electrical conductor after the cutting as in Claim 40.

Further, as shown in Fig. 2 of Gautron, the guide wire 13 is located between the left side of the steel sheet T and the cut D so that the guide wire 13 could not possibly be cut during the shearing operation. Accordingly, guide wire 13 could not possibly suggest a monitor line for testing after completion of cutting as recited in Claim 40 since it is always conductive after cutting. Additionally, Gautron only discloses the use of the electrically conductive guide wire 13 on a conductive steel sheet. As a result, an electrical test of the guide wire 13 could not be performed after cutting since its connections to the conductive steel sheet would mask any results. In at least the foregoing respects, it is not seen that Gautron's guide wire 13 for cutting could possibly teach or suggest the feature of cutting an insulating substrate on which two-dimensionally arranged thin film elements are

installed combined with the feature of electrically checking after cutting of a monitor line that has an electrical conductor and is provided on a side of the insulating substrate where the thin film semiconductor elements are installed. It is therefore believed that Claim 40 as currently amended is completely distinguished from Gautron and is allowable.

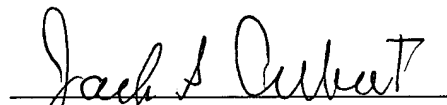
A review of the other art of record has failed to reveal anything which, in Applicants' opinion, would remedy the deficiencies of the art discussed above, as references against the independent claim herein. That claim is therefore believed patentable over the art of record.

The other claims in this application are each dependent from the independent claim discussed above and are therefore believed patentable for the same reasons. Since each dependent claim is also deemed to define an additional aspect of the invention, however, the individual reconsideration of the patentability of each on its own merits is respectfully requested.

In view of the foregoing amendments and remarks, Applicants respectfully request favorable reconsideration and early passage to issue of the present application.

Applicant's attorney, Steven E. Warner, may be reached in our Washington, D.C. office by telephone at (202) 530-1010. All correspondence should be directed to our address listed below.

Respectfully submitted,

A handwritten signature in cursive script, reading "Jack S. Cubert", written over a horizontal line.

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